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**FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #20102**Generic Copy

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**Issue Date:** 16-Aug-2013**TITLE:** MFP10SK Products transfer from Taihei Electronics Co., Ltd to Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP).**PROPOSED FIRST SHIP DATE:** 16-Nov-2013**AFFECTED CHANGE CATEGORY(S):** MFP10SK assembly site, facilities, materials**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact your local ON Semiconductor Sales Office or  
<Tetsuro.Maruyama@onsemi.com>  
<Naoki.Koyama@onsemi.com>

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available  
Contact your local ON Semiconductor Sales Office or  
<Satoru.Fujinuma@onsemi.com>

**NOTIFICATION TYPE:**

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

**DESCRIPTION AND PURPOSE:**

Products transfer from Taihei Electronics Co.,Ltd to Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP).

Taihei Electronics Co.,Ltd , sub-con in Japan closed their outsource business at the end of Jun 2013 (MFP10SK). MFP10SK products will be transferred to Sanyo Semiconductor Manufacturing Philippines Corp.

Equipment and materials will be changed by transferring site and have proven sufficient in other packages in Sanyo Semiconductor Manufacturing Philippines Corporation (SSMP).  
There is no change to the package external dimensions and shipping form.



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### RELIABILITY DATA SUMMARY:

#### **Reliability Test Results:**

Test Items	Test Conditions	Test	Failure
Temperature Humidity Bias ※	Ta=85°C, RH=85%, VCC=Recommended.	500hrs	0
Temperature Cycle ※	Ta=-55°C 30min ⇔ Ta=150°C 30min.	200cyc	0
Pressure Cooker ※	Ta=-121°C RH=100% 2.03x10 <sup>5</sup> Pa	200hrs	0
High Temperature Storage	Ta=150°C	500hrs	0
Resistance to Soldering heat (Reflow Soldering)	260°C, 10s	2 times	0

Notice) The test items with ※ mark are put into operation after the reflow soldering (at 260°C for 10s).  
Judgment Criteria : Judgment Criteria are due to the limits of the electricities in the detail specifications.

This FPCN will be updated after reliability evaluation was completed.

Reliability test is still in progress.

Estimated date for completion: 30/Aug/2013

### ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in the electrical performance. Datasheet specifications remain unchanged.

### CHANGED PART IDENTIFICATION:

Products manufactured at SSMP will be marked with 'L7' preceding the Lot No. on shipping label.

### List of affected General Parts:

LA6583MC-AH  
LA6588MC-AH  
LA6588MC-BH  
LB11861MC-AH  
LB1846MC-AH  
LB1862MC-AH  
LB1948MC-AH  
LB1948MC-BH  
LB1948MC-ZH  
LC87F2608AUMM-AH



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**List of affected Customer Specific Parts:**

LA6588M-TE-L-H  
LB11861M-TLM-H  
LB1862M-TLM-H  
LC87F2608A59W3MM-AH  
LC87F2608A5BW9MM-AH